

View Online at https://aerobasegroup.com/nsn/5910-01-253-4137

# Body Style:

Chip type

**Reliability Indicator:** 

Established

### **Reliability Failure Rate Level In Percent:**

0.001

### **Terminal Length:**

0.020 inches

**Body Length:** 

0.080 inches

**Body Width:** 

0.050 inches

#### **Body Height:**

Between 0.020 inches and 0.080 inches

### Schematic Diagram Designator:

No common or grounded electrode (s)

### Insulation Resistance At Maximum Operating Temp:

10000.0 megohms

### **Capacitance Value Per Section:**

12.000 picofarads single section

### Nonderated Operating Temp:

Between -55.0 degrees celsius and 125.0 degrees celsius

### Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:

0.0 single section

### Nonderated Continuous Voltage Rating And Type Per Section:

100.0 dc single section

# Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:

-30.0/+30.0 single section

# **Tolerance Range Per Section:**

-5.00/+5.00 percent single section

# Case Material:

Ceramic

# Insulation Resistance At Reference Temp:

100000.0 megohms

# Dissipation Factor At Reference Tempurature In Percent:

0.150

# **Terminal Surface Treatment:**

Solder

### **Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

# Terminal Type And Quantity:

2 bonding pad



# **Specification Data:**

81349-mil-c-55681/1 government specification

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

A010b0